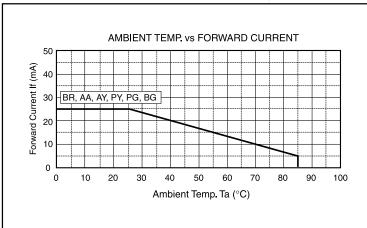
Absolute Maximum Ratings

(Ta=25°C)

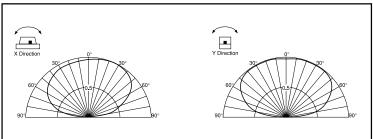
Item		Red	Orange	Yellow	Yellow Green	Green	Pure Green	Units
Rem	Symbol	BR	AA	AY	PY	PG	BG	
Power Dissipation	Pd	57.5	70	70	70	70	70	mW
Forward Current	I F	25	25	25	25	25	25	mA
Peak Forward Current	I FM	60	60	60	60	60	60	mA
Reverse Voltage	V R	4	4	4	4	4	4	V
Operating Temperature	Topr	-30 to +85						°C
Storage Temperature	Tstg	-40 to +100						°C
Derating*	ΔI _F	0.36 (DC) 0.86 (Pulse)						mA/°C

^{*} Ta=25°C, I_{FM} applies for the pulse width ≤ 1msec. and duty cycle ≤1/20.

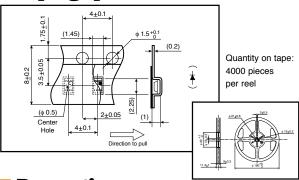
Operation Current Derating Chart (DC)



Spatial Distribution



■ Taping Specifications

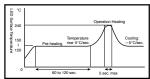


Precautions

Please follow these handling precautions to prevent damage to the chip and ensure its reliability.

1. Soldering conditions:

- <u>Soldering iron</u>: Temperature at tip of iron: 280°C max. (30W max.) Soldering time: 3 sec. max.
- <u>Dip soldering</u>: Preheating: 120 ~ 150°C max. (resin surface temp.)
 60 ~ 120 sec. max. Bath temperature: 260°C max. Dipping Time: 5 sec. max.
- · Reflow Soldering:



2. Cleaning:

- If cleaning is required, use the following solutions for less than 1 minute, at less than 40°C.
- Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

Product specifications subject to change without notice. PG1112H-0301



Stanley Electric Sales of America, Inc.